



High Voltage Trench Schottky Diode

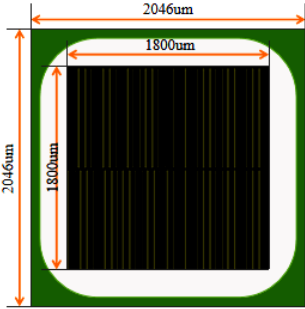
FEATURES

- Trench MOS Schottky technology
- Die in 6" Wafer Form
- 150V, 5A*
- $V_F=0.74V$ (typ.)**

Electrical Characteristics (T_j=25°C)

Parameter	Description	Min.	Typ.	Max.	Unit	Test Condition
V _{RRM}	Maximum repetitive peak reverse voltage	155	167	—	V	I _R =500μA
V _F	Static Forward Voltage	—	0.46	0.50	V	I _F =1A
		—	0.61	0.64	V	I _F =3A
		—	0.74	0.77	V	I _F =5A
I _R ***	Cathode-To-Anode Leakage Current	—	3	30	μA	V _R =150V
T _J , T _{STG}	Operating and Storage Temperature Range	-55°C to 150°C Max				
*** Pulse width < 300 uS, Duty cycle < 2%						

Mechanical Data

Die Size	2106×2106	μm ²	CHIP DRAWING (Scribe Line is Excluded) 
Source Pad Size	1800 × 1800	μm ²	
Scribe Line Size	60	μm	
Wafer Diameter	6	in	
Wafer Thickness	250	μm	
Estimated Gross Die	3611(Yield>98%)		
Anode Metal Thickness	AlSiCu(5.5um)		
Cathode Metal Thickness	Ti\Ni\Ag(0.2um\0.3um\2um)		
Recommended Storage Environment	Store in original container, in dry nitrogen, < 6 months at an ambient temperature of 23°C±3°C >		

* Electrical characteristics are reported for the reference packaged part (TO-220) and can not be guaranteed in die sales form.

** Electrical characteristics are reported for the bare die. Variations in customer packaging materials, dimensions and processes may affect parametric performance.